



Aries 16 x 16 BGA Zero Insertion Force Production Socket

FEATURES:

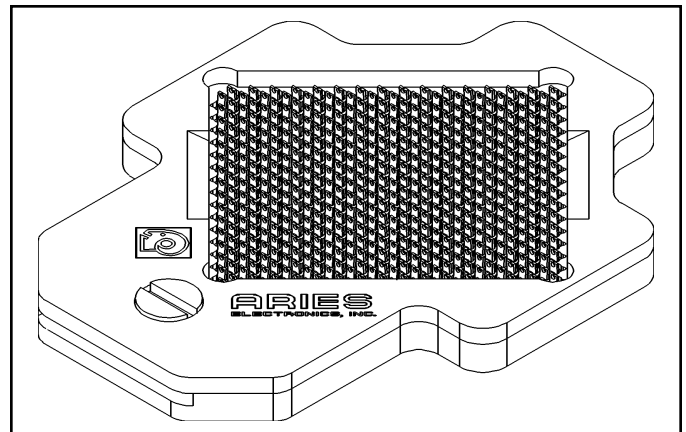
- Turn the slotted cam with a flat screwdriver and the ZIF BallLock contacts remain open, allowing effortless, accurate BGA device insertion. By turning the slotted cam back to its original position, the dual-beam, bifurcated, zero-insertion force BallLock contacts grip, hold and assure contact with the BGA device balls at all times.
- Lidless design allows for heat sink attachment to BGA device, if required.
- Extraction recesses incorporated to ease the removal of the BGA device.
- Can be used for any 16 x 16 or smaller BGA device on 1.27mm [.050] pitch. Consult factory for other available grid sizes and 1.50mm [.059] pitch BGA sockets.
- Low-profile socket only adds .100 [2.54] to overall device height.

SPECIFICATIONS:

- Socket body is UL 94V-0 LCP.
- ZIF pin material is Beryllium Copper Alloy 172 HT per QQ-C-533.
- ZIF pin plating is either 100 μ [2.54 μ m] min. 90/10 Tin/Lead per MIL-T-10727 or 30 μ [.76 μ m] min. Gold per MIL-G-45204 over 30 μ [.76 μ m] min. Nickel per QQ-N-290.
- Solder ball terminations are 90/10 Tin/Lead.
- Inductance $\leq 1\eta$ H/continuous (approximately).
- Capacitance ≤ 1 pf/contact @ 100 MHz (approximately).
- Contact resistance ≤ 20 mOhms.
- Durability = 20 cycles max.
- Socket accepts BGA devices with .030 to .035 [.76 to .89] balls.

MOUNTING CONSIDERATIONS:

- See suggested PCB layout below.



Note: Aries specializes in custom design and production. In addition to the standard products shown on this page, special materials, platings, sizes, and configurations can be furnished, depending on quantities. Aries reserves the right to change product specifications without notice.

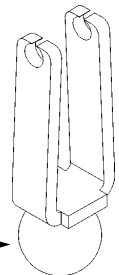
ORDERING INFORMATION

Specify Part No. 256-BGZIF16-70V when ordering socket with Tin plating

-or-

Part No. 256-BGZIF16-71V when ordering socket with Gold plating

Consult Data Sheet Nos. 23000 thru 23011 and BGA footprint catalog for the complete line of Aries BGA interconnect products.

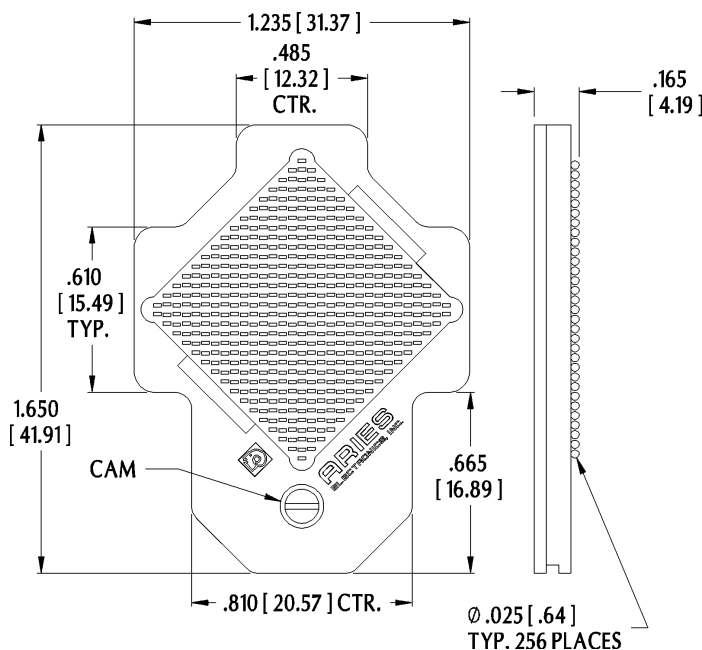


Solder ball termination

BallLock™ CONTACT

ALL DIMENSIONS: INCHES [MILLIMETERS]

All tolerances $\pm .005$ [.13] unless otherwise specified



SUGGESTED PCB LAYOUT (top view)

